CPI0805G1R8R-10

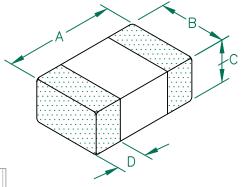
PHYSICAL DIMENSIONS:

A 2.00 [.079] ± 0.20[.008]

B 1.25 [.049] ± 0.20[.008]

C 0.90 [.035] ± 0.10[.004]

D 0.50 [.020] ± 0.20[.008]



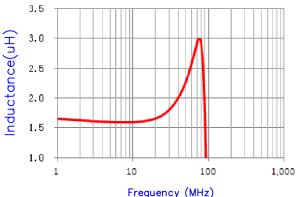
	ELECTRICAL CHARACTERISTICS:									
	L (μΗ) @ 1MHz ± 20%	DCR (Ω)	l (Max)							
Nom	1.8									
Min	1.4									
Max	2.2	0.275	700mA							

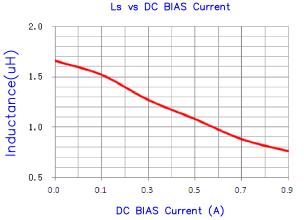
NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
- 2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
- 5. Operation Temperature TEMP: -55°C~+125°C. (INCLUDING SELF-HEATING)
- 6. COSMETIC SPECIFICATION REFER TO WI-QA-124.

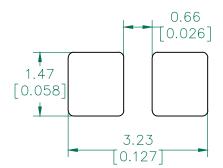
 ERING RECOMMENDED SOLDERING CONDITIONS

Ls vs Frequency

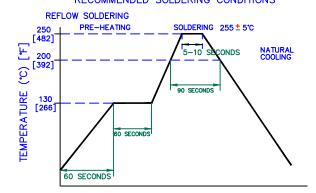




LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering. add 0.763 [0.030] to this dimension)





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ł					PROJECT/PART NUMBER:	Т	REV	PART T	rPE:	DRAWN BY:
ł	С	CHANGE PLASTIC TAPE TO PAPER TAPE	04/17/14	QU	T CPI0805G1R8R-10		С	CO-FIRE		QU
ı	•	CHANGE PLASTIC TAPE TO PAPER TAPE			or recognition to	- 1		1		
ı	В	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU	DATE: 03/01/11	SCAL	ALE: NTS		SHEET:	
ſ	Α	ORIGINAL DRAFT	03/01/11	QU	, ,	TOO				
Ī	REV	DESCRIPTION	DATE	INT	CPI0805G1R8R-10-A	.50		_	1	of 1